

OPTICAL EPOXY RESINS, GLOB TOP, STRUCTURAL BONDING - TWO-COMPONENT*

REF	MIX RATIO	CURING SCHEDULE Recommended	POT LIFE After mixing	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
								BEFORE TG	AFTER TG		
E501	4/1	12/24 h at 25°C	1 h at 25°C	0,2 Pa.S	50-70°C	310-330°C		70-80.10 ⁻⁶ /°C	240-260.10 ⁻⁶ /°C	10 ¹³ Ω.cm	bonding of optical devices - Glass clear, liquid - Also in more thixotropic versions, but opaques : E501Si, E501SiT, E501T and E501TT
E504	5/1	48 h at 25°C	2 h at 25°C	4 Pa.S	60-70°C	340-360°C	24%	60-70.10 ⁻⁶ /°C	120-140.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Semi-flexible - UL94VO - Liquid - White
E504T	10/0,5	48 h at 25°C	2 h at 25°C	8 Pa.S	70-80°C	340-360°C	27%	60-70.10 ⁻⁶ /°C	120-140.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Semi-flexible - UL94VO - Thixotropic - White
E505	10/1	1 min at 150°C	4 h at 25°C	1,6 Pa.S	105-115°C	380-400°C		60-70.10 ⁻⁶ /°C	140-160.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Excellent wicking in fiber optic bundles - Also black versions and thixotropic versions : E505Si, E505SiT, E505T and E505TT
E507	1/0,28	2 h at 125°C	4 h at 25°C	1,2 Pa.S	105-115°C	380-400°C				10 ¹⁶ Ω.cm	Bonding of ferrite parts
E507-4	1/1	10 min at 150°C	8 h at 25°C	22,5 Pa.S	160-170°C	370-380°C	81%	17-20.10 ⁻⁶ /°C	65-70.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	Chip protection smart cards
E510	10/1,1	24/48 h at 25°C	1 h at 25°C	6 Pa.S	90-100°C	340-360°C	45%	50-60.10 ⁻⁶ /°C	150-180.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Casting passive components - Liquid - Rigid - Black
E511	10/0,6	48 h at 25°C	1 h at 25°C	13 Pa.S	60-80°C	340-360°C	45%	50-60.10 ⁻⁶ /°C	150-180.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Casting passive components - Thixotropic - Rigid - Black
E512	10/2	48 h at 25°C	15 at 30 min at 25°C	5 Pa.S	60-70°C	340-360°C	20%	60-70.10 ⁻⁶ /°C		10 ¹³ Ω.cm	Casting passive components - Liquid - Semi flexible - Black
E512-2	10/0,5	48 h at 25°C	1 h at 25°C	5 Pa.S	60-70°C	340-360°C	20%	60-70.10 ⁻⁶ /°C		10 ¹³ Ω.cm	Casting passive components - UL94Vo
E513	1/1	20 min at 140°C	8 h at 25°C	30 Pa.S	125-130°C	400-410°C	70%	35-40.10 ⁻⁶ /°C	100-120.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	high voltage insulators - White - Good thermal conductivity
E514	1/1	2 h at 100°C+4 h at 160°C	8 h at 25°C	100 Pa.S	150-160°C	340-350°C	65%	20-30.10 ⁻⁶ /°C	60-70.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	Glop top resin for semi conductors chips - black - High purity
E515	4/1	12/24 h at 25°C	1 h at 25°C	40 Pa.S	50-70°C	310-330°C	16%	70-80.10 ⁻⁶ /°C	240-260.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Very thixotropic resin - white
E516	100/3	30 min at 120°C	16 h at 25°C	80 Pa.S	70-90°C	400-410°C	73%	30-40.10 ⁻⁶ /°C	100-120.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	Transformers - High thermal conductivity - Blue
E520	1/1	3 à 6 h at 25°C	10 min at 25°C	9 Pa.S						10 ¹³ Ω.cm	Glass clear resin - Short gel time
E521	3,35/1	2 h at 65°C	20 min at 20°C	27 Pa.S	100°C	340-360°C	44%	50-60.10 ⁻⁶ /°C	150-160.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	For protection - White - Low thermal expansion
E522	2,43/1	20 min at 65°C	20 at 30 min at 25°C		120°C	340-360°C		70-80.10 ⁻⁶ /°C	150-160.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	For protection - White - Low thermal expansion - High temperature
E525	10/1	45 min at 85°C	4 h at 25°C	30 Pa.S	105-120	400°C		65-70.10 ⁻⁶ /°C		10 ¹² Ω.cm	Bonding of larges pieces. High temperature
E526	2/1	15 min at 65°C	20 min at 25°C	40 Pa.S	95°C	400°C		20.10 ⁻⁶ /°C		8.10 ¹⁴ Ω.cm	Low thermal expansion - high chemical resistance

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

* for more precision on the technical properties, to refer to the individual data sheet.

Maj 24/04/2008